



TBL SYSTEMS
INTEGRATED INTELLIGENCE

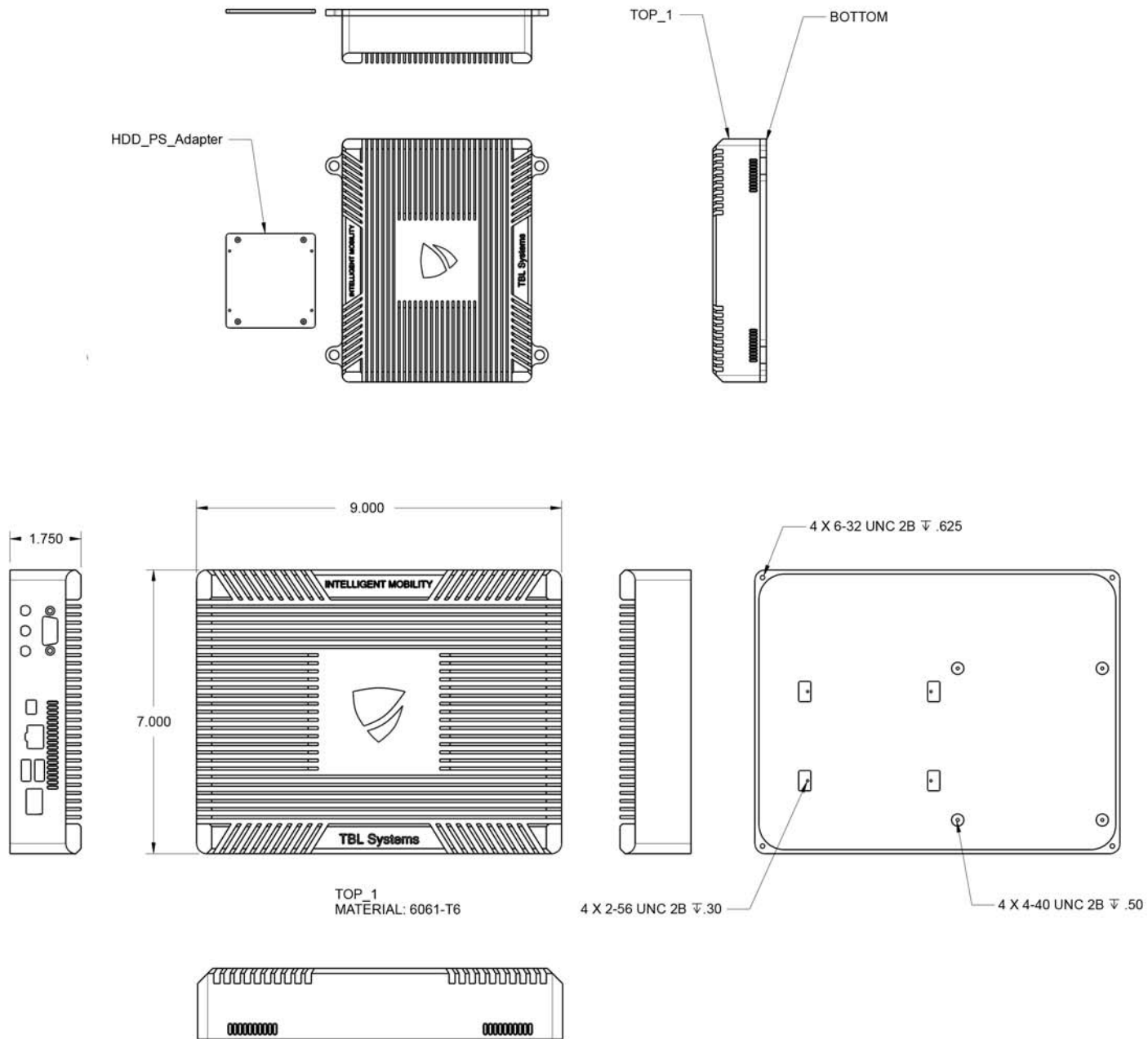
TBL Systems eMDC Product Interface Specifications



TBL SYSTEMS

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MDC/MDT & Mobile LTE Hot Spot

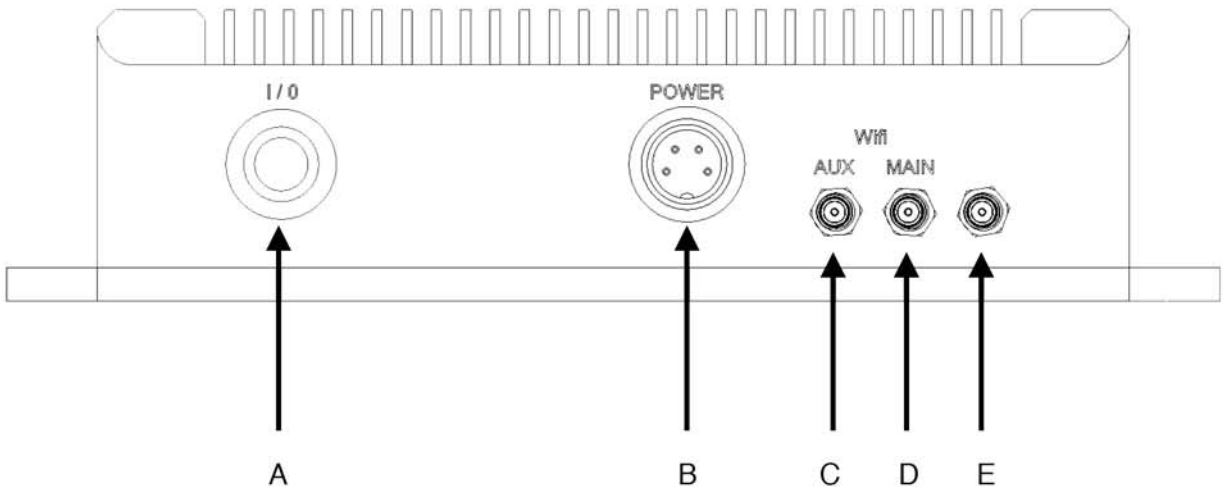




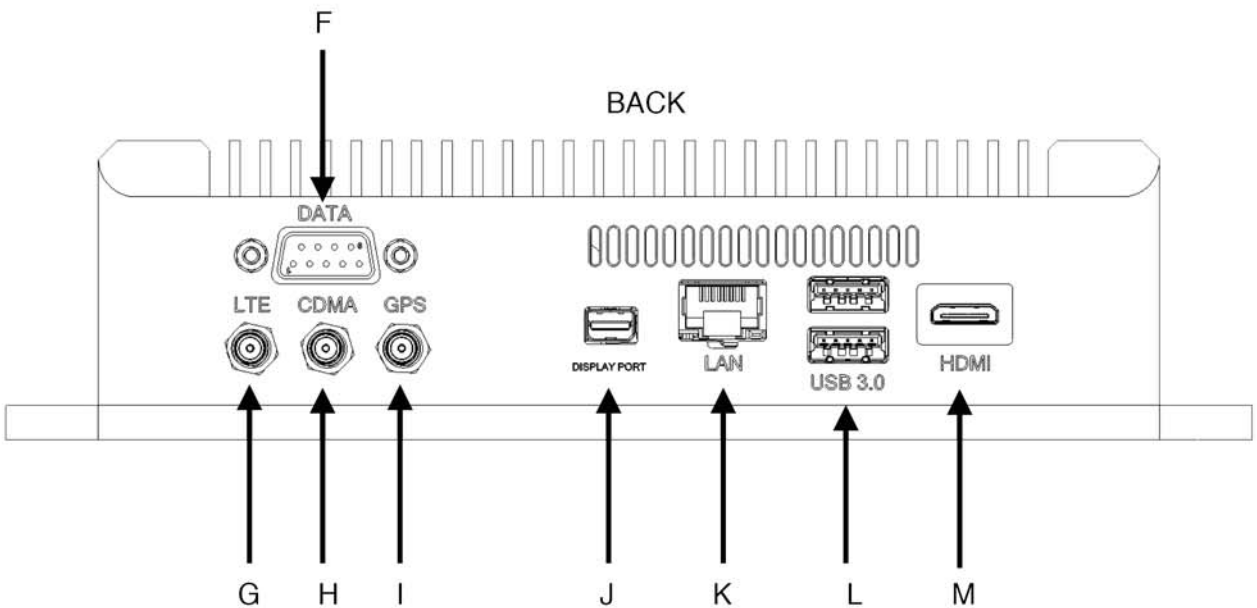
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FRONT



BACK





COMPONENT INFORMATION

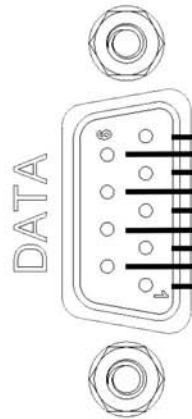
LOCATION	DESCRIPTION
FRONT PANEL	
A	POWER ON/OFF BUTTON
B	POWER CONNECTOR
C	AUX WIFI SMA RF CONNECTOR
D	MAIN WIFI SMA-RF CONNECTOR
E	SPARE
BACK PANEL	
F	D-SUB-MINIATURE (FEMALE) DATA CONNECTOR
G	LTE SMA-RF CONNECTOR
H	CDMA SMA-RF CONNECTOR
I	GPS SMA-RF CONNECTOR
J	DISPLAY PORT
K	LOCAL AREA NETWORK (LAN)
L	USB 3.0
M	MINIATURE HDMI



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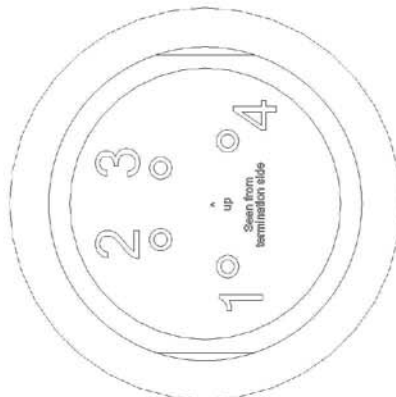
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F FEMALE D-SUB 9



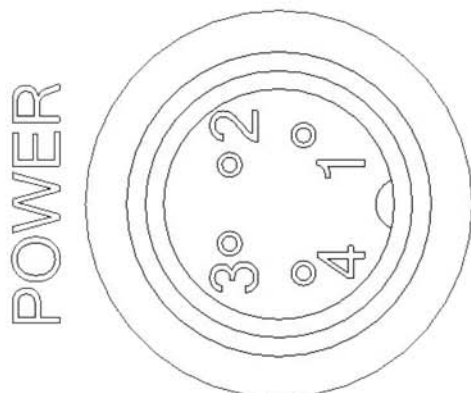
POS	DESCRIPTION
5	
9	
4	
8	
3	
7	
2	
6	
1	

B POWER (BACK VIEW)



POS	DESCRIPTION
4	+ 12VDC IN
3	IGNITION
2	THUMP
1	GND

B POWER (FRONT VIEW)

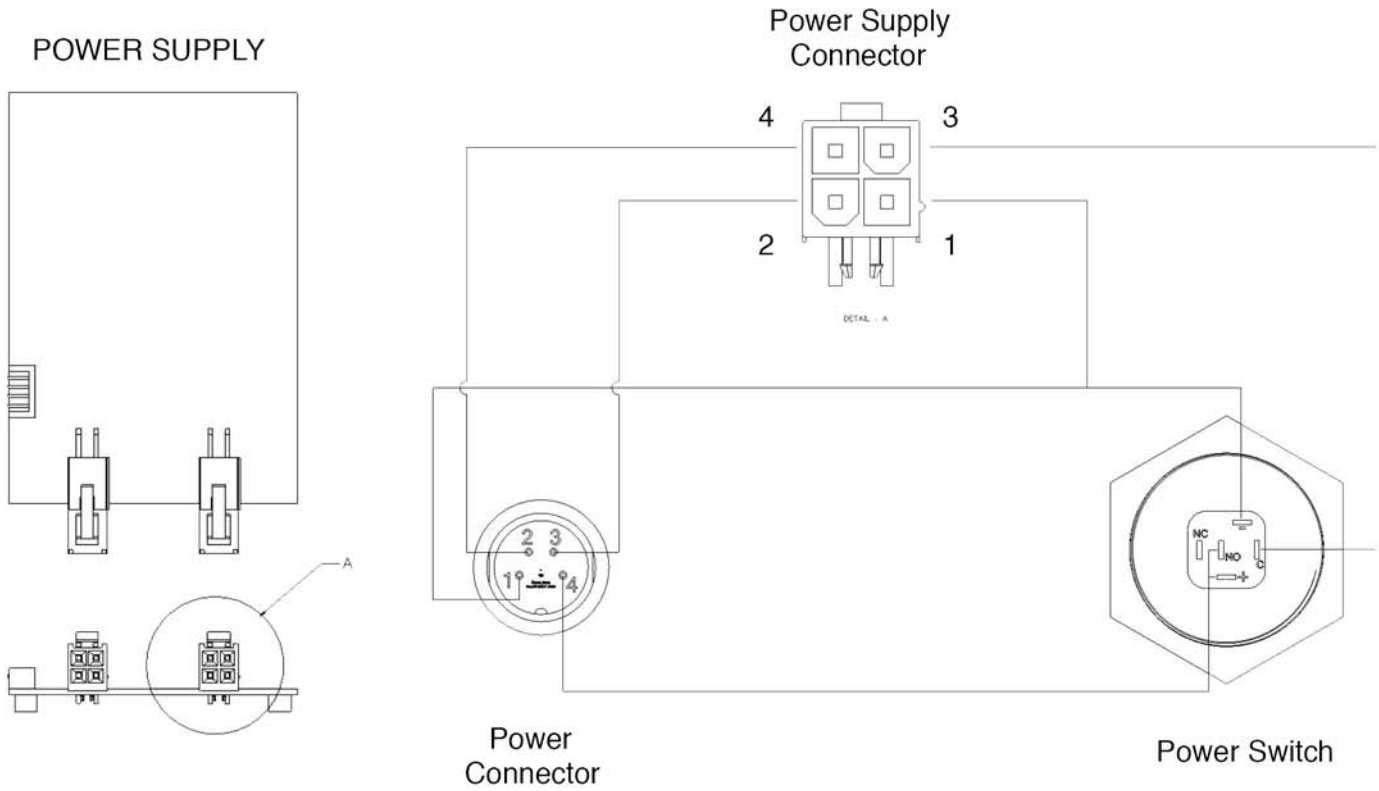


POS	DESCRIPTION
1	GND
2	THUMP
3	IGNITION
4	+ 12VDC IN



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POWER DISTRIBUTION

LOCATION	DESCRIPTION
POWER CONNECTOR (BACK)	
1	GND
2	THUMP
3	IGNITION
4	+ 12VDC IN
POWER SWITCH	
NO	+ 12VDC IN
NC	NOT USED
C	SWITCHED POWER TO POWER SUPPLY
-	GND
+	+ 12VDC IN
POWER SUPPLY CONNECTOR (LOOKING AT BOARD)	
1	GND
2	IGNITION
3	SWITCHED POWER TO POWER SUPPLY
4	THUMP



MDC/MDT & Mobile LTE Hot Spot

SPECIFICATIONS	
Computing	
Processor	5 th Generation Intel Core i7-5557u processor with 4 MB Cache, 28w TDP
Graphics	Intel Iris Graphics 6100
System Memory	16 GB 1600 MHz DDR3L SO-DIMM
Storage	1TB Solid State Hard Drive
Connectivity	
Mobile Data	HSPA+: Up to 21.0 Mbps downlink/5.76 Mbps uplink coverage through multiple service providers
Wireless	Intel Dual band 802.11ac, 867 Mbps
LAN	1 Gigabit LAN port
USB	2 Super Hi-Speed USB 3.0 ports
Bluetooth	Dual Mode Bluetooth 4.0
Video	1 Mini HDMI 1.4a port
Radio Compliance	FCC Part 22, FCC Part 24, RSS 132, RSS 133, EN 301 511, EN 301 489-1, EN 301 489-7, EN 301 489-24
Environmental	
Operational Temperature	-40° to +60° C
Storage Temperature	-40° to +85° C
Relative Humidity	20% to 90% RH, non-condensing
Reliability	
Mean Time Between Failures (MTBF)	Telcordia SR-332 Issue 2, Method I, Case 3, 55 °C ambient of 68,076 hours